

## HCG450FF170E3RE1

1700V/450A Half Bridge IGBT Module

### Description

The HCG450FF170E3RE1 is a Half Bridge IGBT Power Module. It integrates high performance IGBT chips designed for the applications such as High Power supply and Motor control.



### Features

- Blocking voltage 1700V
- Low saturation voltage  $V_{CE(sat)}$
- Low Switching Losses
- 175 °C maximum junction temperature
- Thermistor inside

### Applications

- High Power Switching Applications
- Motor Drives
- Solar inverter Systems
- Wind Turbines

### Circuit diagram

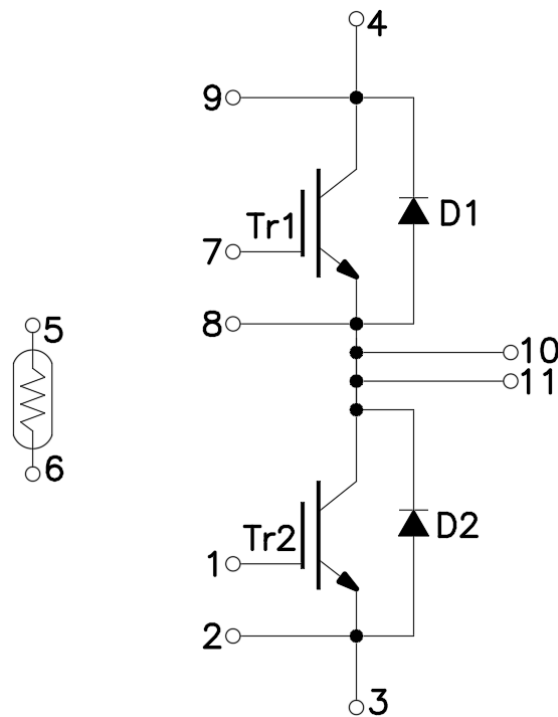


Figure 1. Out drawing & circuit diagram for HCG450FF170E3RE1

**HCG450FF170E3RE1**  
 1700V/450A Half Bridge IGBT Module

**Pin Configuration and Marking Information**

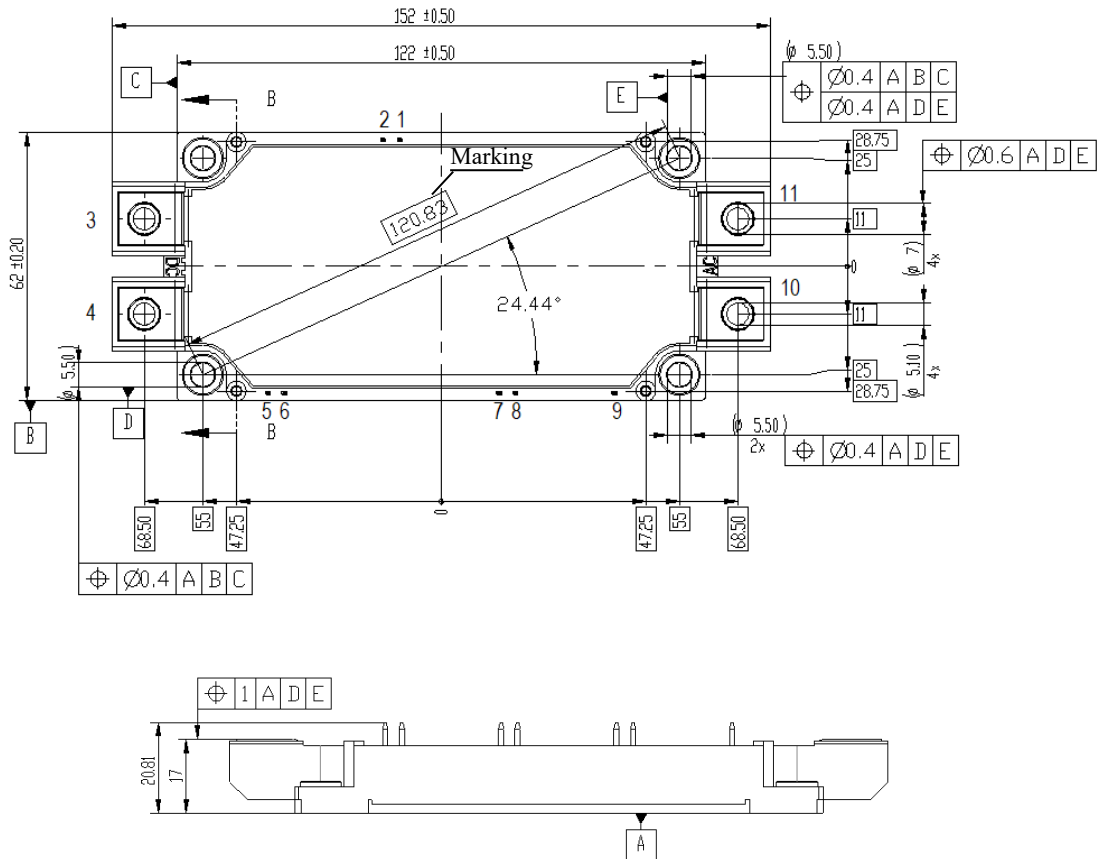


Figure 2. Pin configuration

# HCG450FF170E3RE1

## 1700V/450A Half Bridge IGBT Module

### Module

Parameter	Conditions	Value	Unit
Isolation voltage	RMS, f=50Hz, t=1min	4.0	KV
Material of module baseplate	-	Cu	-
Creepage distance	terminal to heatsink terminal to terminal	14.5 13	mm
Clearance	terminal to heatsink terminal to terminal	12.5 10	mm
CTI	-	>225	-
Module lead resistance, terminals – chip	T <sub>C</sub> =25°C	0.8	mΩ
Mounting torque for module mounting	M5, M6	3 to 6	Nm
Weight	-	420	g

### Maximum Ratings (T<sub>j</sub>=25°C unless otherwise specified)

Symbol	Parameter	Conditions	Ratings	Unit
V <sub>CES</sub>	Collector-Emitter Voltage	G-E Short	1700	V
V <sub>GES</sub>	Gate-Emitter Voltage	C-E Short	±20	V
I <sub>C</sub>	DC Continuous Collector Current	T <sub>C</sub> =95°C	450	A
I <sub>CM</sub>	Pulse Collector Current	t <sub>p</sub> =1ms, Note 1	900	A
P <sub>C</sub>	Maximum Power Dissipation	T <sub>C</sub> =25°C	2632	W
I <sub>F</sub>	Diode Forward Current	-	450	A
I <sub>FRM</sub>	Repetitive peak forward current	t <sub>p</sub> =1ms, Note 1	900	A
I <sup>2</sup> t	I <sup>2</sup> t-value	V <sub>R</sub> =0V, t <sub>p</sub> =10ms, T <sub>j</sub> =125°C(Diode)	20000	A <sup>2</sup> s
T <sub>jmax</sub>	Max junction temperature	-	175	°C
T <sub>vjop</sub>	Operating junction temperature	-	-40 to 175	°C
T <sub>stg</sub>	Storage temperature	-	-40 to 125	°C

Note 1: Pulse width limited by maximum junction temperature

### NTC characteristics

Symbol	Parameter	Condition	Value			Unit
			Min.	Typ.	Max.	
R <sub>25</sub>	Resistance	T <sub>C</sub> =25°C	-	5	-	kΩ
ΔR/R	Deviation of R100	T <sub>C</sub> =100°C, R <sub>100</sub> =493 Ω	-5	-	5	%
P <sub>25</sub>	Power dissipation	T <sub>C</sub> =25°C	-	-	20	mW
B <sub>25/50</sub>	B-value	R <sub>2</sub> =R <sub>25</sub> exp [B <sub>25/50</sub> (1/T <sub>2</sub> - 1/(298,15 K))]	-	3375	-	K
B <sub>25/80</sub>	B-value	R <sub>2</sub> =R <sub>25</sub> exp [B <sub>25/80</sub> (1/T <sub>2</sub> - 1/(298,15 K))]	-	3411	-	K
B <sub>25/100</sub>	B-value	R <sub>2</sub> =R <sub>25</sub> exp [B <sub>25/100</sub> (1/T <sub>2</sub> - 1/(298,15 K))]	-	3433	-	K

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**IGBT Electrical characteristics** ( $T_j=25^\circ\text{C}$  unless otherwise specified, chip: Target)

Symbol	Item	Condition		Value			Unit
				Min.	Typ.	Max	
$V_{CE(sat)}$ (Chip)	Collector-Emitter Saturation Voltage	$I_C=450\text{A}$ $V_{GE}=15\text{V}$	$T_j=25^\circ\text{C}$	-	1.60	1.90	V
			$T_j=150^\circ\text{C}$	-	2.03	-	
			$T_j=175^\circ\text{C}$	-	2.08	-	
$V_{GE(th)}$	Gate-Emitter threshold Voltage	$I_C=18\text{mA}, V_{CE}=V_{GE}$		5.2	5.8	6.4	V
$Q_G$	Gate charge	$V_{GE}=-15\text{V to }+15\text{V}$		-	4.6	-	$\mu\text{C}$
$R_{Gint}$	Internal gate resistor	-	$T_j=25^\circ\text{C}$	-	2.2	-	$\Omega$
$C_{ies}$	Input Capacitance	$V_{CE}=25\text{V}, V_{GE}=0\text{V}$ $f=1\text{MHz}$	$T_j=25^\circ\text{C}$	-	36	-	nF
$C_{res}$	Reverse transfer Capacitance			-	1.15	-	nF
$I_{CES}$	Collector- Emitter Cut off Current	$V_{CE}=1700\text{V}, V_{GE}=0\text{V}$	$T_j=25^\circ\text{C}$	-	-	1	mA
$I_{GES}$	Gate-Emitter Leakage Current	$V_{GE}=20\text{V}, V_{CE}=0\text{V}$	$T_j=25^\circ\text{C}$	-	-	1.35	$\mu\text{A}$
$t_{d(on)}$	Turn-on delay time	$V_{CC}=900\text{V}$ $I_C=450\text{A}$ $V_{GE}=+15\text{V}/-8\text{V}$ $R_G=3.3\Omega$ Inductive load	$T_j=25^\circ\text{C}$	-	335	-	ns
			$T_j=150^\circ\text{C}$	-	360	-	
$t_r$	Rise time		$T_j=25^\circ\text{C}$	-	170	-	ns
			$T_j=150^\circ\text{C}$	-	210	-	
$t_{d(off)}$	Turn-off delay time		$T_j=25^\circ\text{C}$	-	655	-	ns
			$T_j=150^\circ\text{C}$	-	800	-	
$t_f$	Fall time		$T_j=25^\circ\text{C}$	-	405	-	ns
			$T_j=150^\circ\text{C}$	-	680	-	
$E_{on}$	Turn-on power dissipation		$T_j=25^\circ\text{C}$	-	205	-	mJ
			$T_j=150^\circ\text{C}$	-	320	-	
$E_{off}$	Turn-off power dissipation		$T_j=25^\circ\text{C}$	-	105	-	mJ
			$T_j=150^\circ\text{C}$	-	153	-	
$R_{th(j-c)}$	Thermal Resistance, Junction to Case(IGBT)			-	0.057	-	$^\circ\text{C}/\text{W}$
$R_{th(c-s)}$	Thermal Resistance, Case to sink(Conductive Grease applied)			-	0.015	-	$^\circ\text{C}/\text{W}$

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## 1700V/450A Half Bridge IGBT Module

### Freewheeling Diode Electrical characteristics (T<sub>j</sub>=25°C unless otherwise specified, chip)

Symbol	Item	Condition	Value			Unit	
			Min.	Typ.	Max.		
V <sub>F</sub>	Diode Forward Voltage	I <sub>F</sub> =450A, V <sub>GE</sub> =0V	T <sub>j</sub> =25°C	-	1.95	-	V
			T <sub>j</sub> =150°C	-	2.21	-	
			T <sub>j</sub> =175°C	-	2.23	-	
t <sub>rr</sub>	Reverse recovery time	(Switch side) V <sub>CC</sub> =900V, I <sub>C</sub> =450A	T <sub>j</sub> =25°C	-	1.09	-	us
			T <sub>j</sub> =150°C	-	1.58	-	
I <sub>RM</sub>	Peak reverse recovery Current	V <sub>GE</sub> =+15V/-8V, R <sub>G</sub> =3.3Ω (FRD side)	T <sub>j</sub> =25°C	-	199	-	A
			T <sub>j</sub> =150°C	-	250	-	
Q <sub>rr</sub>	Recovered charge	V <sub>rr</sub> =900V, I <sub>F</sub> =450A V <sub>GE</sub> =+15V/-8V	T <sub>j</sub> =25°C	-	79	-	uC
			T <sub>j</sub> =150°C	-	184	-	
E <sub>rr</sub>	Reverse recovered energy	Inductive load switching operation	T <sub>j</sub> =25°C	-	35	-	mJ
			T <sub>j</sub> =150°C	-	90	-	
R <sub>th(j-c)</sub>	Thermal Resistance, Junction to Case (Diode)		-	0.075	-	°C/W	
R <sub>th(c-s)</sub>	Thermal Resistance, Case to sink (Conductive Grease applied)		-	0.020	-	°C/W	

### Test Conditions

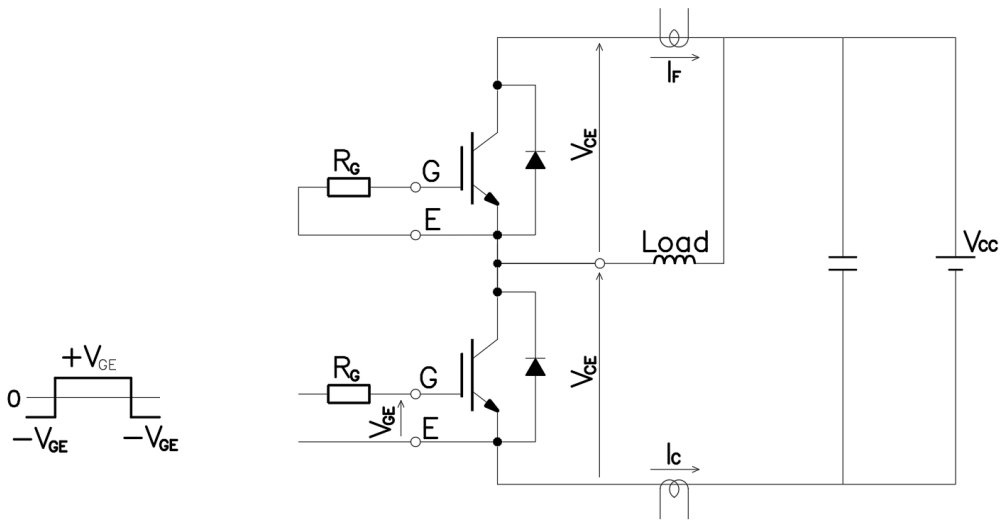


Figure 3. Switching time measure circuit

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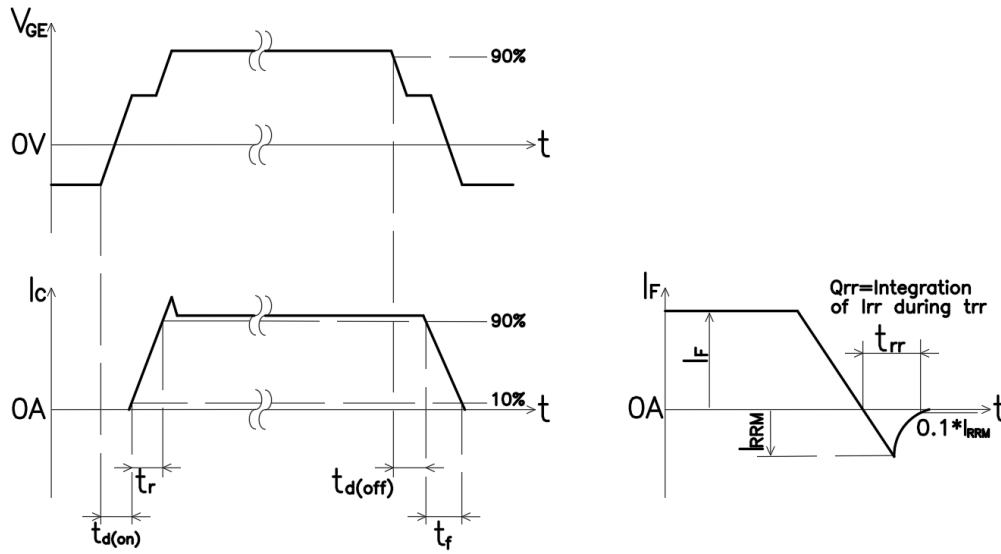


Figure 4. Switching time definition

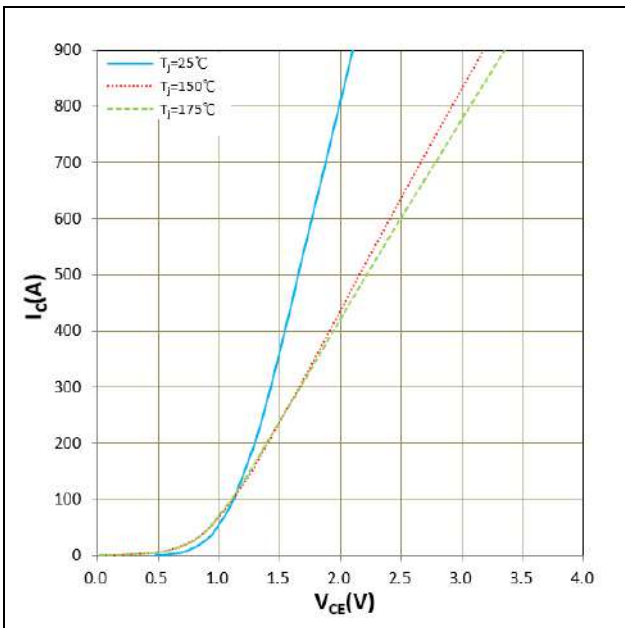


Figure 5.  $I_c$  vs  $V_{CE}$   
 $V_{GE} = 15V$

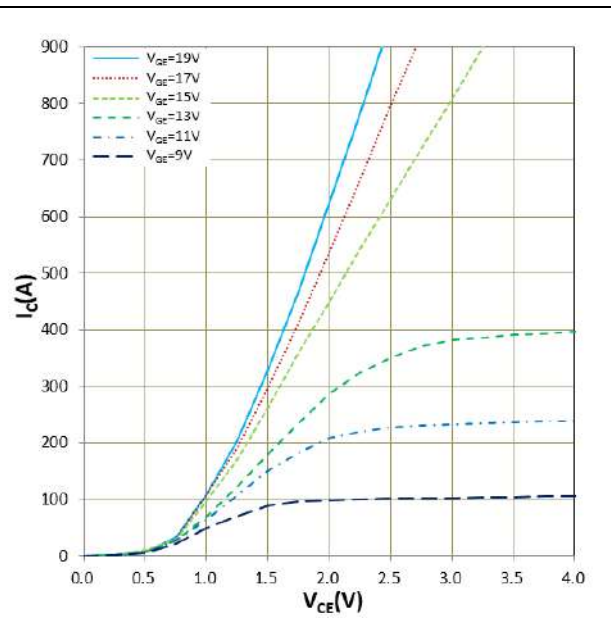


Figure 6.  $I_c$  vs  $V_{CE}$   
 $T_j = 150^\circ C$

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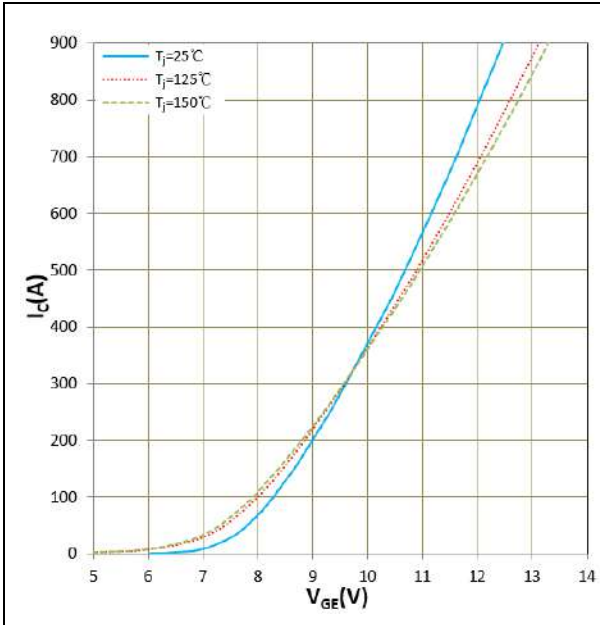


Figure 7.  $I_c$  vs  $V_{GE}$   
 $V_{CE} = 20V$

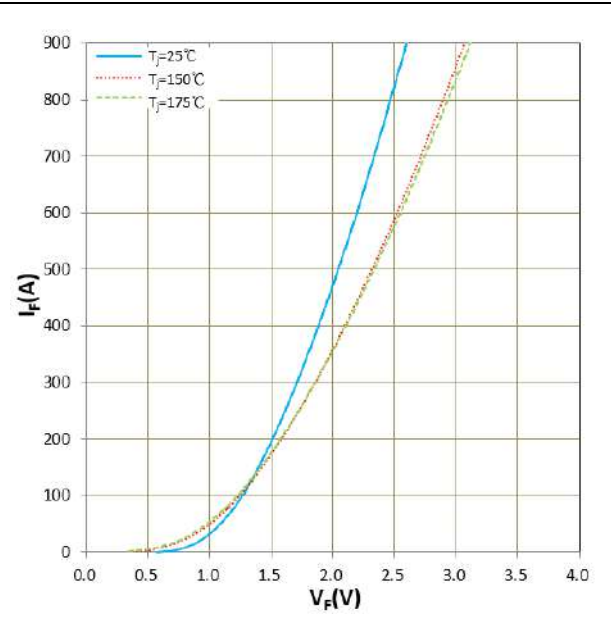


Figure 8.  $I_f$  vs  $V_f$

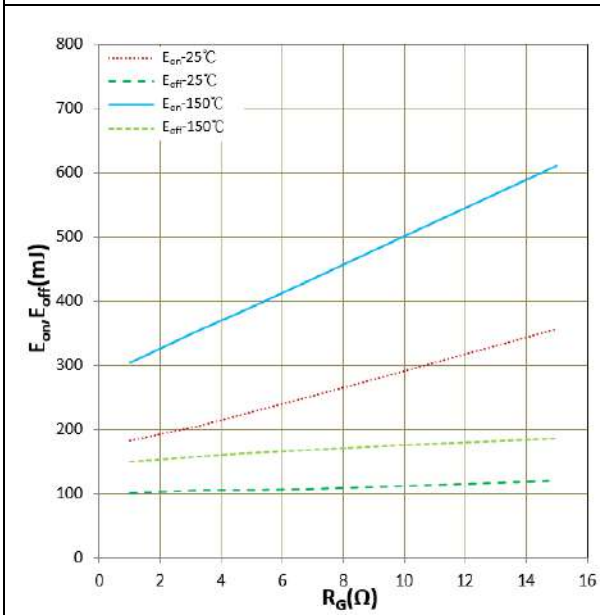


Figure 9.  $E_{on}$ ,  $E_{off}$  vs  $R_G$ (Typ)  
 $V_{CC} = 900V$ ,  $V_{GE} = +15V/-8V$ ,  $I_c = 450A$   
Inductive Load

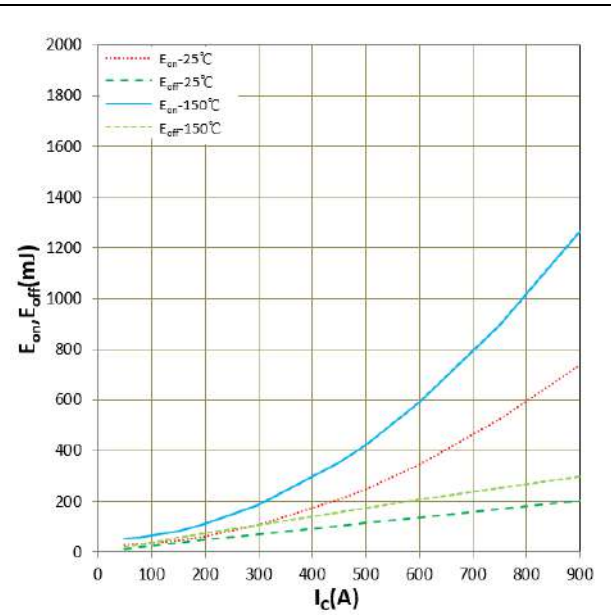


Figure 10.  $E_{on}$ ,  $E_{off}$  vs  $I_c$ (Typ)  
 $V_{CC} = 900V$ ,  $V_{GE} = +15V/-8V$ ,  $R_G = 3.3\Omega$   
Inductive Load

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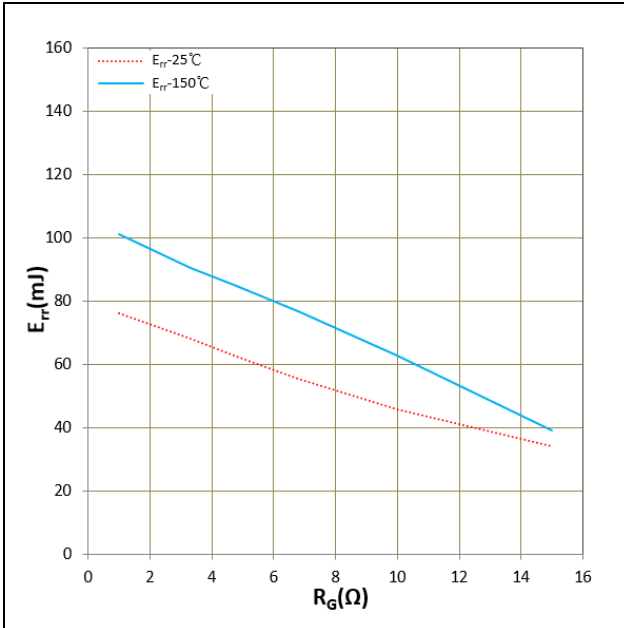


Figure 11.  $E_{rr}$  vs  $R_G$ (Typ)  
 $V_{CC}=900V$ ,  $V_{GE}=+15V/-8V$ ,  $I_F=450A$   
Inductive Load

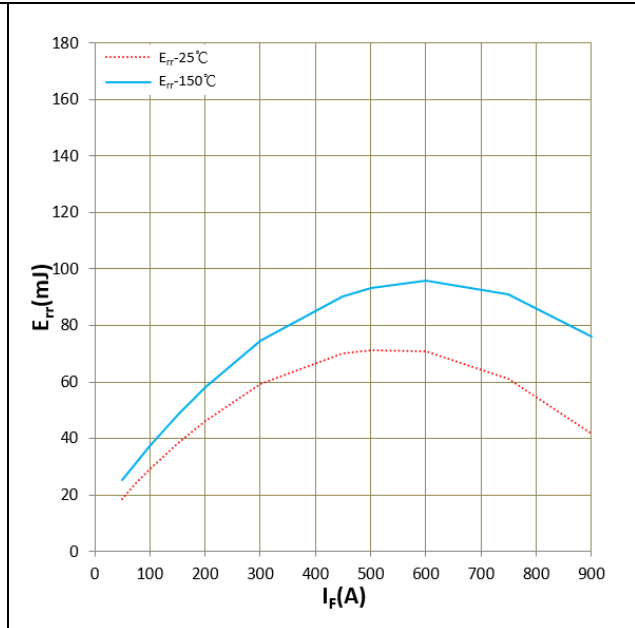


Figure 12.  $E_{rr}$  vs  $I_F$ (Typ)  
 $V_{CC}=900V$ ,  $V_{GE}=+15V/-8V$ ,  $R_G=3.3\Omega$   
Inductive Load

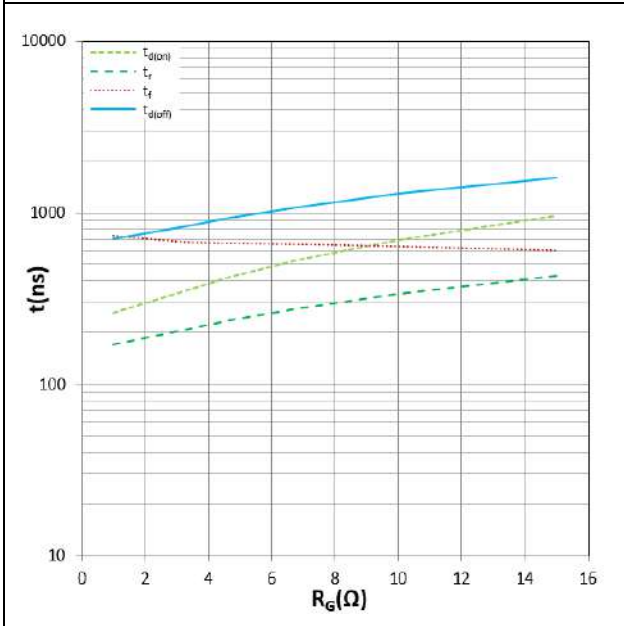


Figure 13. Switching time vs  $R_G$ (Typ)  
 $V_{CC}=900V$ ,  $V_{GE}=+15V/-8V$ ,  $I_C=450A$ ,  
 $T_j=150^\circ C$ , Inductive Load

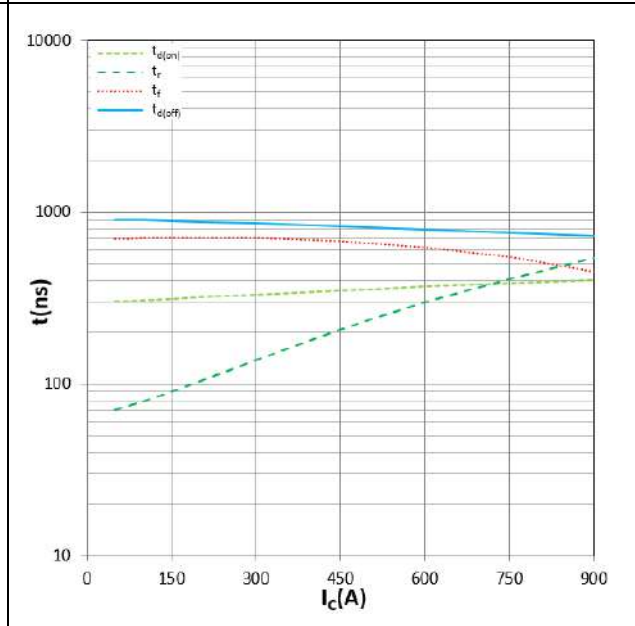


Figure 14. Switching time vs  $I_C$ (Typ)  
 $V_{CC}=900V$ ,  $V_{GE}=+15V/-8V$ ,  $R_G=3.3\Omega$   
 $T_j=150^\circ C$ , Inductive Load



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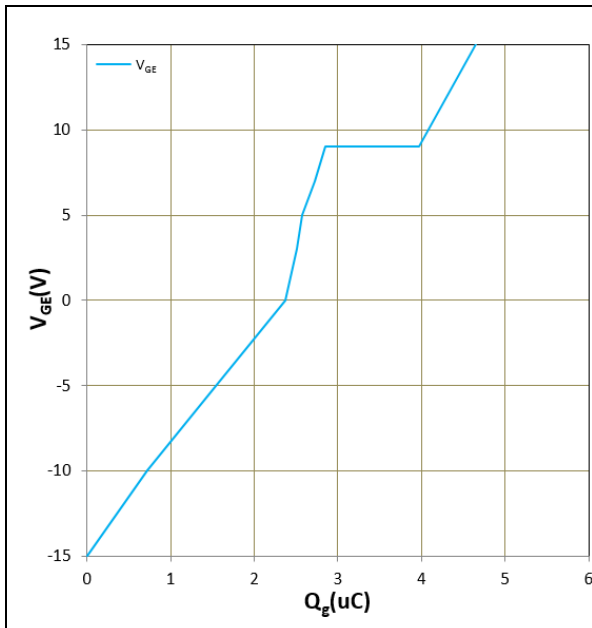
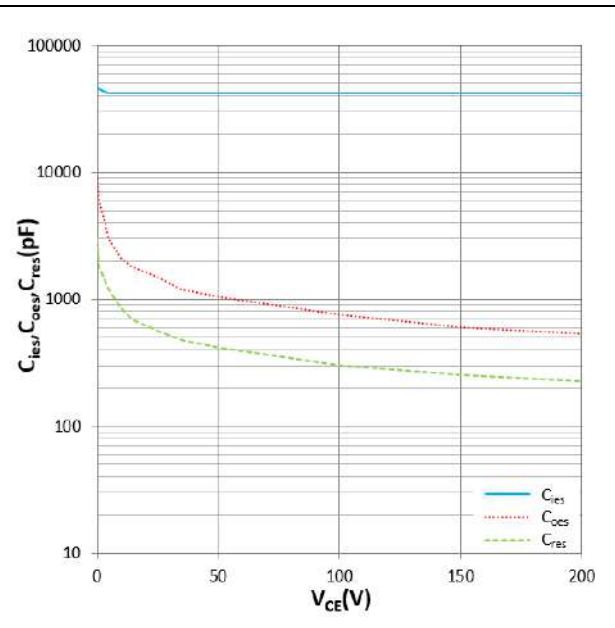


Figure 15. Gate charge


 Figure 16.  $C_{ies}$ ,  $C_{oes}$ ,  $C_{res}$  vs  $V_{ce}$   
 $T_j = 25^\circ\text{C}$ ,  $f = 1\text{MHz}$ 

#### IMPORTANT NOTICE:

This product data sheet describes the characteristics of this product for which a warranty is granted. Any such warranty is granted exclusively under the terms and conditions of the supply agreement. There will be no guarantee or of any kind for the product and its characteristics.

The data contained in this document is exclusively intended for technically trained staff. You and your technical departments will have to evaluate the product's suitability for the intended application and the completeness of the product data concerning such application.

Due to technical requirements, our product may contain dangerous substances. For information on the types in question, please contact the sales staff responsible for you.

Changes to this product data sheet are reserved.

Please contact the sales staff (sales@hiitio.com) for further information on the product, technology, delivery terms, conditions and prices.

## Instruction note

Naming rules for power module product models (Industrial module)

Product Model							
	<b>HC</b>	<b>G</b>	<b>450</b>	<b>FF</b>	<b>1200</b>	<b>E3</b>	<b>A</b>
Hecheng Code							
Module type G : IGBT module D : FRD module S : SiC module H : Si/SiC hybrid							
Current level (A) 50~900							
Topology structure FZ : A switch unit    FF : Half bridge FS : Three phase    F4 : H Bridge F3L : Three level    DF : Boost Circuit FD : Braking Circuit FP : Rectification+Inverter+Control move AL : ANPC    CL : Chopper							
Voltage level (x10) (V) 650~2200							
Packaging form+features (A...Z)							
	A1: 34 mm	A2: 62 mm					
	B1: Easy 1B	B1A			B1B...		
	B2: Easy 2B...	B3: Easy 3B...					
	D1: Flow0	D2: Flow1			D3: Flow2		
	E0: E0	E1: Econo 2...			E2: E2		
	E3: ED3	E4: E4			E5: ED3S		
	E6: EPM2	E7: EPM3			E8: EconoPIM3		
	E9: ED3H	F0: F0			P2: EPM2		
Feature :A: Special Code    Nil: Standard							

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